

TOSHIBA Field-Effect Transistor Silicon P-Channel MOS Type

# SSM6P35FE

- High-Speed Switching Applications
- Analog Switch Applications

- 1.2-V drive
- Low ON-resistance :  $R_{on} = 44 \Omega$  (max) (@ $V_{GS} = -1.2$  V)  
                           :  $R_{on} = 22 \Omega$  (max) (@ $V_{GS} = -1.5$  V)  
                           :  $R_{on} = 11 \Omega$  (max) (@ $V_{GS} = -2.5$  V)  
                           :  $R_{on} = 8 \Omega$  (max) (@ $V_{GS} = -4.0$  V)

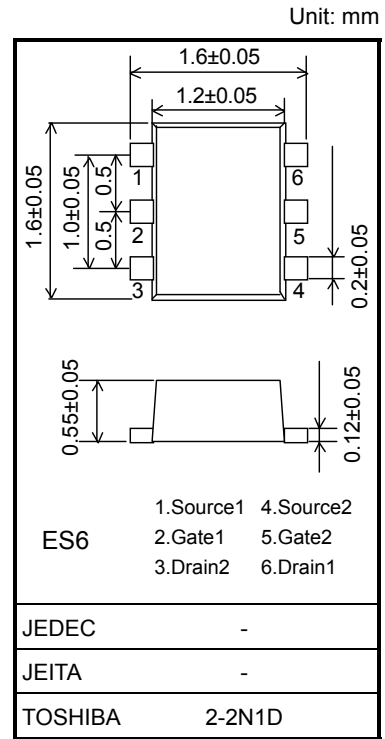
**Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ ) (Common to the Q1, Q2)**

Characteristic	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	-20	V
Gate-source voltage	$V_{GSS}$	$\pm 10$	V
Drain current	DC	$I_D$	-100
	Pulse	$I_{DP}$	-200
Drain power dissipation	$P_D$ (Note 1)	150	mW
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to 150	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

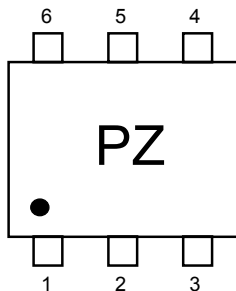
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total rating  
 Mounted on an FR4 board  
 (25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm, Cu Pad: 0.135 mm<sup>2</sup>  $\times$  6)

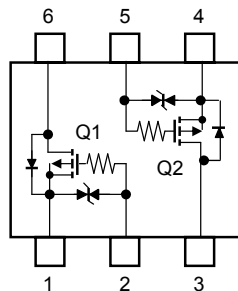


Weight: 3.0 mg (typ.)

**Marking**



**Equivalent Circuit (top view)**



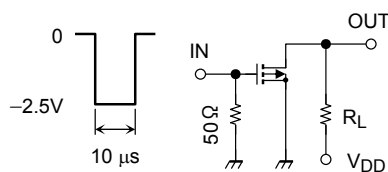
## Electrical Characteristics (Ta = 25°C) (Common to the Q1, Q2)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 10\text{ V}, V_{DS} = 0\text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = -0.1\text{ mA}, V_{GS} = 0\text{ V}$	-20	—	—	V
Drain cutoff current	$I_{DSS}$	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$	—	—	-1	$\mu\text{A}$
Gate threshold voltage	$V_{th}$	$V_{DS} = -3\text{ V}, I_D = -1\text{ mA}$	-0.4	—	-1.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -3\text{ V}, I_D = -50\text{ mA}$ (Note 2)	77	—	—	mS
Drain-source ON-resistance	$R_{DS(ON)}$	$I_D = -50\text{ mA}, V_{GS} = -4\text{ V}$ (Note 2)	—	4.3	8	$\Omega$
		$I_D = -50\text{ mA}, V_{GS} = -2.5\text{ V}$ (Note 2)	—	5.6	11	
		$I_D = -5\text{ mA}, V_{GS} = -1.5\text{ V}$ (Note 2)	—	8.2	22	
		$I_D = -2\text{ mA}, V_{GS} = -1.2\text{ V}$ (Note 2)	—	11	44	
Input capacitance	$C_{iss}$	$V_{DS} = -3\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	12.2	—	pF
Reverse transfer capacitance	$C_{rss}$		—	6.5	—	
Output capacitance	$C_{oss}$		—	10.4	—	
Switching time	Turn-on time	$t_{on}$	$V_{DD} = -3\text{ V}, I_D = -50\text{ mA},$ $V_{GS} = 0\text{ to }-2.5\text{ V}$	—	175	ns
	Turn-off time	$t_{off}$		—	251	
Drain-source forward voltage	$V_{DSF}$	$I_D = 100\text{ mA}, V_{GS} = 0\text{ V}$ (Note 2)	—	0.83	1.2	V

Note 2: Pulse test

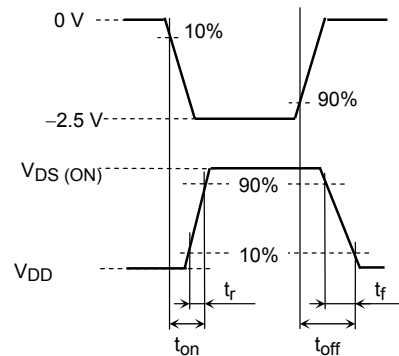
## Switching Time Test Circuit (Common to the Q1, Q2)

### (a) Test Circuit



$V_{DD} = -3\text{ V}$   
 D.U.  $\leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5\text{ ns}$   
 ( $Z_{out} = 50\ \Omega$ )  
 Common Source  
 $T_a = 25^\circ\text{C}$

### (b) $V_{IN}$



### (c) $V_{OUT}$

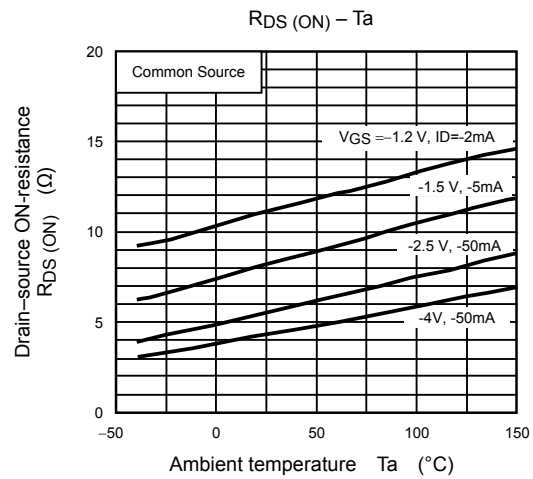
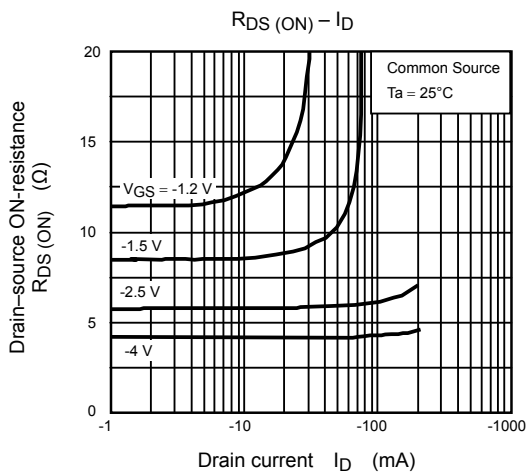
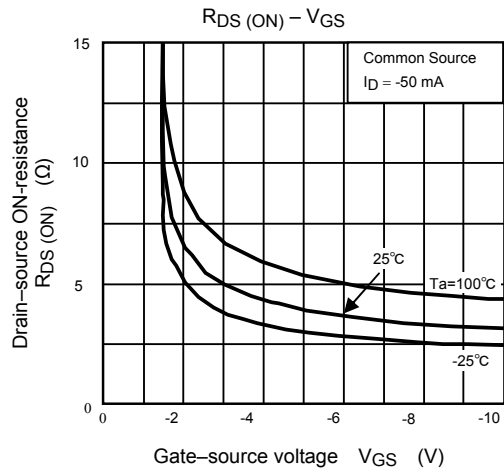
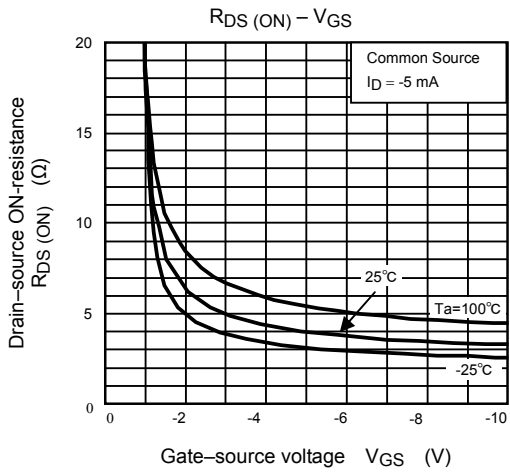
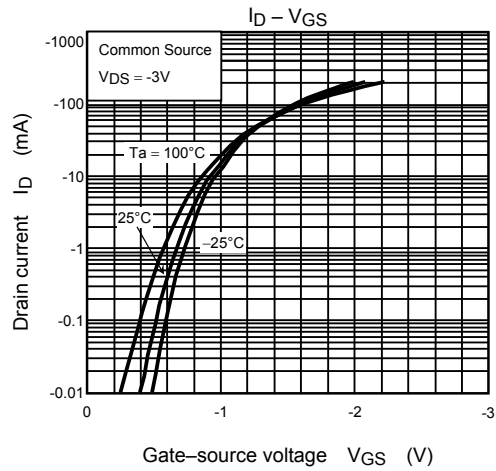
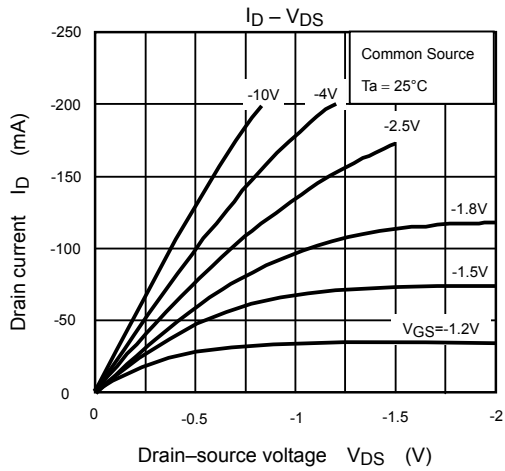
## Usage Considerations

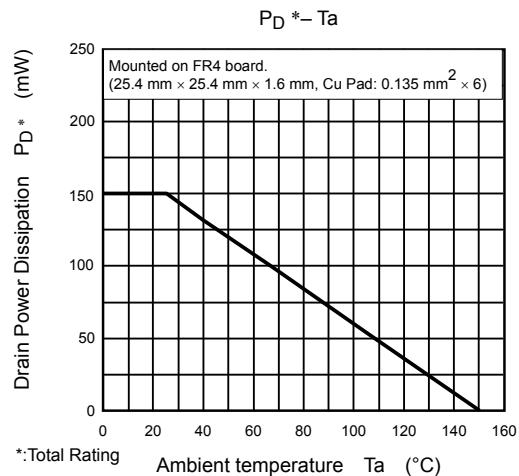
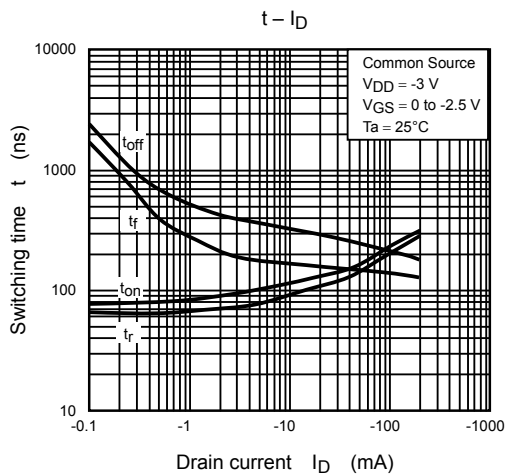
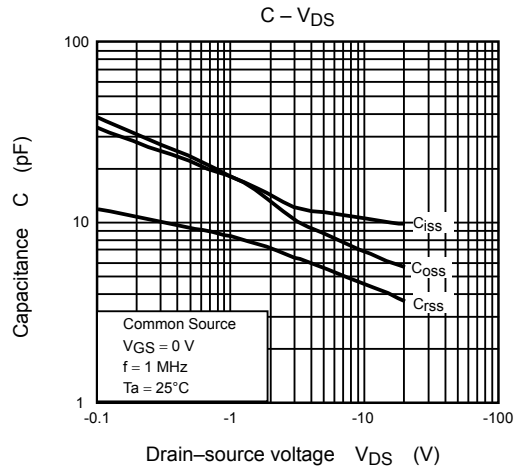
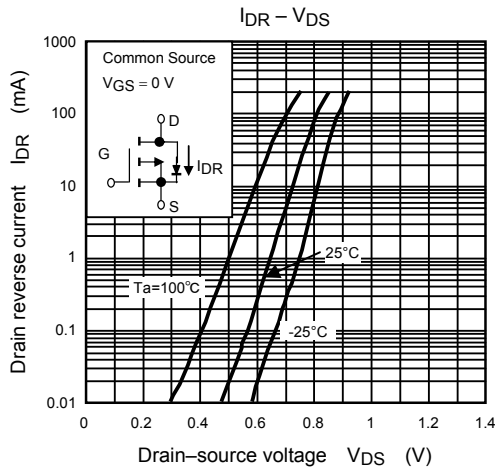
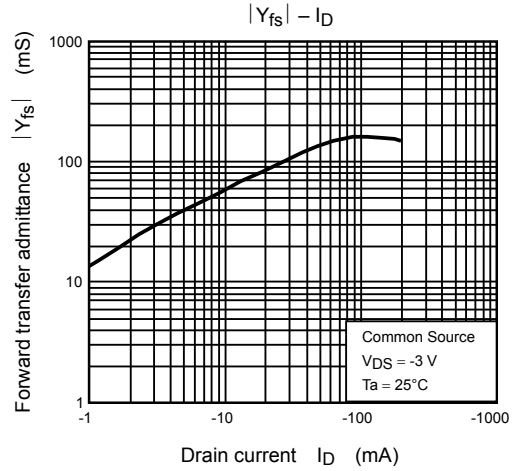
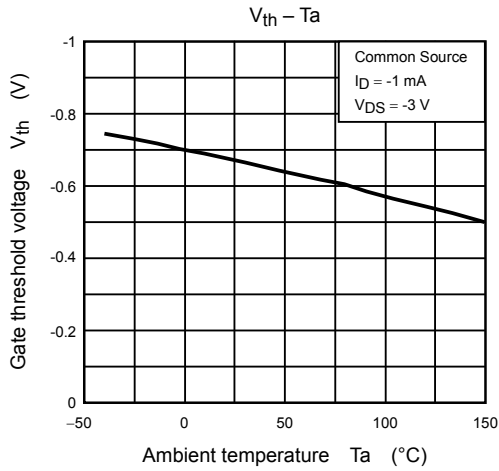
Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to below ( $-1\text{ mA}$  for the SSM6P35FE). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ .

Take this into consideration when using the device.

## Handling Precaution

When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.





**RESTRICTIONS ON PRODUCT USE**

20070701-EN GENERAL

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- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.  
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